

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Masahiko HATA	11/18/2011
Tomoyuki TAKADA	11/18/2011
Sadanori YAMANAKA	11/20/2011
Taro ITATANI	11/21/2011

RECEIVING PARTY DATA

Name:	SUMITOMO CHEMICAL COMPANY, LIMITED
Street Address:	27-1, Shinkawa 2-chome
City:	Chuo-ku, Tokyo
State/Country:	JAPAN
Postal Code:	104-8260

Name:	National Institute of Advanced Industrial Science and Technology
Street Address:	3-1, Kasumigaseki 1-chome
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PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13310522

CORRESPONDENCE DATA

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OP \$40.00 13310522

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**PATENT
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ATTORNEY DOCKET NUMBER:	Q128045
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NAME OF SUBMITTER:	Byron F. Galvez
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Total Attachments: 2 source=Q128045_ASSIGNMENT_AS_FILED#page1.tif source=Q128045_ASSIGNMENT_AS_FILED#page2.tif
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ASSIGNMENT OF US NON PROVISIONAL APPLICATION

Attorney Docket No. _____
 Client Ref. S23433US01
 JP Atty. Ref. SC-0045PCTUS

In consideration of the sum of Ten Dollars (\$10.00) and other good and valuable consideration paid to me as an undersigned inventor, the receipt and sufficiency of which are hereby acknowledged who at the request of, hereby sells, assigns and transfers unto:

SUMITOMO CHEMICAL COMPANY, LIMITED
 27-1, Shinkawa 2-chome, Chuok-ku, Tokyo 104-8260 Japan

(hereinafter designated "ASSIGNEE") my entire right, title and interest for the United States of America as defined in 35 U.S.C. 100, in the invention and all applications including any and all divisions, continuations, substitutes, and reissues thereof; and all resulting patents, known as

SENSOR, SEMICONDUCTOR WAFER, AND METHOD OF PRODUCING SEMICONDUCTOR WAFER

for which I executed an inventor's declaration for Patent Application of the United States of America

- (A) even date herewith
 (B) in US or International Appln. No. filed on

AND I hereby authorize and request the United States Commissioner of Patents and Trademarks to issue said Letters Patent to the said ASSIGNEE (and any other assignee, if otherwise assigned), for its interest as ASSIGNEE, its successors, assigns and legal representatives; I agree that the attorney of record in said application shall hereinafter act on behalf of said ASSIGNEE;

AND I hereby agree to testify and execute any papers for ASSIGNEE, its successors, assigns and legal representatives, deemed essential by ASSIGNEE to ASSIGNEE'S full protection and title in and to the invention hereby transferred.

I hereby authorize the US attorney of record to insert hereon any further identification necessary or desirable for recordation of this document.

INVENTORS 発明者サイン	DATE SIGNED 日付	WITNESS 発明者サインを目視した人(省略可)
1): <u>Masahiko HATA</u> Name: Masahiko HATA	<u>Nov. 18, 2011</u>	Name: _____
2): <u>Tomoyuki Takada</u> Name: Tomoyuki TAKADA	<u>November 18, 2011</u>	Name: _____
3): <u>Sadanori Yamanaka</u> Name: Sadanori YAMANAKA	<u>November 20, 2011</u>	Name: _____
4): _____ Name: _____	_____	Name: _____
5): _____ Name: _____	_____	Name: _____
6): _____ Name: _____	_____	Name: _____
7): _____ Name: _____	_____	Name: _____
8): _____ Name: _____	_____	Name: _____
9): _____ Name: _____	_____	Name: _____
10): _____ Name: _____	_____	Name: _____
11): _____ Name: _____	_____	Name: _____
12): _____ Name: _____	_____	Name: _____

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National Institute of Advanced Industrial Science and Technology
 3-1, Kasumigaseki 1-chome, Chiyoda-ku, Tokyo 100-8921 JAPAN

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SENSOR, SEMICONDUCTOR WAFER, AND METHOD OF PRODUCING SEMICONDUCTOR WAFER

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AND I hereby agree to testify and execute any papers for ASSIGNEE, its successors, assigns and legal representatives, deemed essential by ASSIGNEE to ASSIGNEE'S full protection and title in and to the invention hereby transferred.

I hereby authorize the US attorney of record to insert hereon any further identification necessary or desirable for recordation of this document.

INVENTORS 発明者サイン DATE SIGNED 日付 WITNESS 発明者サインを目視した人(省略可)

1): Name: Taro ITATANI	Nov 21st 2011	Name: _____
2): Name: _____	_____	Name: _____
3): Name: _____	_____	Name: _____
4): Name: _____	_____	Name: _____
5): Name: _____	_____	Name: _____
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9): Name: _____	_____	Name: _____
10): Name: _____	_____	Name: _____
11): Name: _____	_____	Name: _____
12): Name: _____	_____	Name: _____

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